

C5735

Conductors

Description

C5735 is a gold conductor paste that has been formulated for use with Au wire bonding applications. C5735 is a screen printable paste that gives an extremely dense and defect-free fired film. Fine lines are able to be printed down to 75 µm lines and spaces with etching possible for ultra-fine features down to 25 µm.

Key Features

- Excellent Au bondability
- High conductivity
- Fine line printing
- Etchable (Chemical and laser)



This picture does not show the packaging of C5735 and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties (Paste)

Resistivity	≤ 4.5 mΩ/□ at 10 µm fired film thickness using 25 mil wide serpentine conductor pattern
Viscosity	300 – 530 Kcps, Anton Paar Physica MCR101, CP25-1, 4sec-1, 25 °C
Au Wire Bondability	1.25 mil Wire, 99.99% purity, Elongation limit 2.0 – 7.0% 96 % Al ₂ O ₃ Initial: >12g
Solids	84.5 ± 1 %
Coverage	118 cm ² /g @ 10 µm fired film thickness

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Recommended Processing Guidelines

Printing	325 – 400 mesh stainless steel screen 0.3 – 0.5 mil emulsion 1.1 mil wire
Settling	A settling time of 10 – 15 minutes is recommended. Parts should be dried as soon as possible after the setting period, (within 20 minutes), so the paste does not skin over. Parts should not be left out for long periods of time before drying. This allows the paste to skin over and can compromise adhesion. Wet parts should be covered if not dried right away.
Drying	150 °C for 10 minutes Make sure ventilation is sufficient to prevent the wet film from skinning
Firing	850 °C peak temperature, 10 minutes at peak Total cycle time of 45 – 60 minutes
Thickness	Wet: 22 – 28 µm Dry: 11 – 15 µm Fired: 6 – 10 µm
Thinner	RV-507
Compatibility	IP9217, IP9227 multilayer dielectrics

Warranty

Material guaranteed to meet specifications for 6 months from date of shipment.

Storage

Refrigerate at 1 -5°C to ensure shelf life. Allow paste to come to room temperature prior to opening. Spatulate well before using, as settling may occur during storage.

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